

SUPERIOR GaN TP44400SG – 360 mΩ, 650 V GaN HEMT

1.0 Features

- 650 V e-mode power HEMT
- $R_{DS(on)}$: 360 mΩ
- I_{DS} : 6.5 A (max) / $I_{DS(pulse)}$: 7.5 A (max)
- ESD protection on all pins
- Adjustable turn-on/-off speed
- Reverse conduction capability
- Zero reverse-recovery loss
- High switching frequency capability
- LV-isolated thermal-pad for better thermal connection even with current-sense resistors
- Interfaces with 6 V and ≥ 12 V drivers (see [Application Information](#))

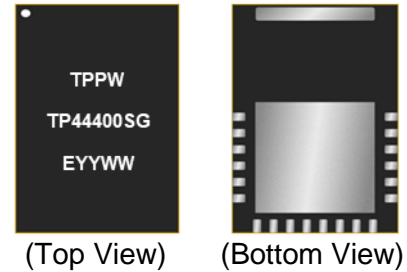


Figure 1 Device Image
(22 pin 5x7x0.8 mm QFN Package)

2.0 Topologies and Applications

- Ac-dc, dc-dc, dc-ac converters
- PFC and inverter applications
- ACF and AHB based power supplies
- High frequency LLC resonant converters
- Mobile chargers and laptop adapters
- Half- and full-bridge dc-dc converters
- LED and motor drives



RoHS/REACH/Halogen Free Compliance

3.0 Description

The TP44400SG is a 360 mΩ 650 V SUPERIOR GaN HEMT power device. With low input/output capacitances and a low inductance QFN package, the device allows high frequency switching. Simple external interface circuit can be used to drive this device both from dedicated 6 V GaN drivers as well as more traditional 12 V drivers. No external VCC is needed in either case. Resistors in the turn-on/-off gate paths can be used to control the switching slew-rates for the best EMI performance. The device is well suited for GaN based power applications with a view towards high performance and reduced system cost.

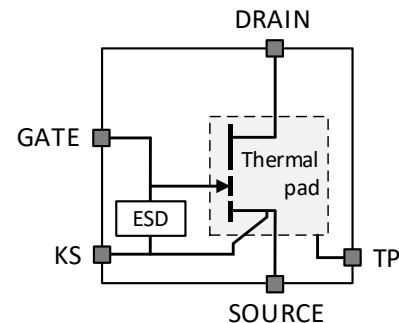


Figure 2 Functional Block Diagram

4.0 Ordering Information

Table 1 Ordering Information

Base Part Number	Package Type	Form	Qty	Reel Diameter	Reel Width	Orderable Part Number
TP44400SG	22 Pin 5x7x0.8 mm QFN	Tape and Reel	1000	13" (330 mm)	18 mm	TP44400SGTRPBF

5.0 Pin Definition

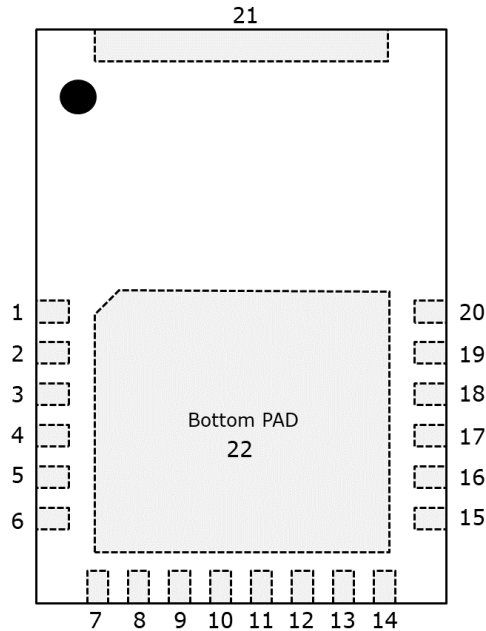


Figure 3 Pin Location
(Package Top View)

Table 2 Pin Definition

Pin Number	Pin Name	Pin Type	Description
1-4, 7, 11-20	NC	NC	No connect. These pins can be connected to TP (Pin 22) at PCB level for better thermal performance.
5	GATE	AI	Gate of the power HEMT device.
6	KS	AI	Kelvin-source of the power HEMT device. To be used for driver return path.
8-10	SOURCE	PWR	Source of the power HEMT device.
21	DRAIN	PWR	Drain of the power HEMT device.
22	TP	Thermal	Exposed thermal pad of the power HEMT device. Must have good thermal path to the PCB thermal plane or a heat sink. Also, voltage difference between this pin and SOURCE (Pins 8 to 10) shall be limited within ± 20 V. See the section on Application Information for more details.

Abbreviations: NC = not connected; AI = analog input; PWR = power

6.0 Absolute Maximum Ratings

Table 3 Absolute Maximum Ratings ^[1] @T_J = +25 °C, unless otherwise specified.

Parameter	Symbol	Value	Unit
Electrical Ratings			
Drain to source voltage of GaN power HEMT	V _{DS}	650	V
Transient drain to source voltage ^[2]	V _{TDS}	750	V
Continuous drain current (at T _c = 25 °C)	I _{DS}	6.5	A
Continuous drain current (at T _c = 100 °C)	I _{DS}	4	A
Pulsed drain current (at T _J = 25 °C) ^[3]	I _{DSpulse}	7.5	A
Drain to source voltage slew-rate	(dv/dt) _{DS}	200	V/ns
Input gate voltage with respect to the source or the Kelvin-source	V _{GS}	-0.5 to +6.5	V
Transient input gate voltage with respect to the source	V _{GS(Transient)}	+9.0 ^[4]	V
Voltage difference of TPL pad to SL Pin	ΔV _{TPL-Source}	±20	V
Storage temperature range	T _{st}	-55 to +150	°C
Operating temperature range	T _{op}	-55 to +150	°C
Maximum junction temperature	T _J	+150	°C
Thermal Ratings			
Thermal resistance (junction-to-case) – bottom side	R _{θJC}	2.5	°C/W
Thermal resistance (junction-to-ambient) ^[5]	R _{θJA}	40	°C/W
Soldering temperature	T _{SOLD}	260	°C
ESD Ratings			
Human body model (HBM) per JS-001-2017	Level 1C	1500 to 2000	V
Charged device model (CDM) per JS-002-2014	Level C3	≥1000	V
Moisture Rating			
Moisture sensitivity level (per J-STD-020D.1)	MSL	1	-

Note:

[1] These are stress ratings. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Exceeding one or a combination of the absolute maximum ratings may cause permanent and irreversible damages to the device and/or to the surrounding circuit.

[2] For duration < 1ms, provided to indicate robustness and not recommended for normal operation.

[3] For duration < 10us, followed by sufficient time for the device to cool off.

[4] The negative transient voltage gets clamped due to the internal ESD.

[5] As measured on DUT soldered on 2 oz Cu (FR4) PCB of size 1 square inch.

7.0 Recommended Operating Conditions

Table 4 Recommended Operating Conditions ^[1] @T_J = +25 °C, unless otherwise specified.

Parameter	Symbol	Min	Nominal	Max	Unit
Input gate to Kelvin-source voltage	V _{GS}	0		6.0	V
Pull-up resistor – with 12 V drive ^[2]	R _U	50			Ω
Pull-up resistor – with 6 V drive ^[2]		20			Ω
Operating case temperature	T _C	-40		+125	°C

Note:

[1] Operating for extended periods of time at conditions beyond the recommended range might affect device reliability.

[2] The recommended value of this resistor depends on the drive type and the interface circuit. See the section on [Application Information](#) for more details.

8.0 Electrical Specifications

Table 5 Electrical Specifications ^[1] @T_J = + 25°C, unless otherwise specified.

Parameter	Description	Condition	Minimum	Typical	Maximum	Unit
Static Characteristics						
R _{DS(on)}	Drain to source resistance	I _{DS} = 0.5 A DC, V _{GS} = 6 V, T _J = +25 °C		360	472	mΩ
		I _{DS} = 0.5 A DC, V _{GS} = 6 V, T _J = +150 °C		880		
I _{DSS}	Drain to source leakage current	V _{DS} = 650 V, V _{GS} = 0 V, T _J = +25 °C		0.1		μA
		V _{DS} = 650 V, V _{GS} = 0 V, T _J = +150 °C		15.0		
V _{GS(th)}	Gate threshold voltage	V _{DS} = V _{GS} , I _{DS} = 2.8 mA		1.7	2.5	V
I _{GS}	Gate to source current	V _{DS} = 0 V, V _{GS} = 6 V		7		μA
Dynamic Characteristics						
C _{ISS}	Input capacitance	V _{DS} = 400 V, V _{GS} = 0 V, Freq = 100 kHz		28		pF
C _{RSS}	Reverse transfer capacitance			0.16		pF
C _{OSS}	Output capacitance			9		pF
C _{O(ER)} ^[2]	Effective output capacitance – energy related	V _{DS} = 0 to 400 V, V _{GS} = 0 V		13		pF
C _{O(TR)} ^[3]	Effective output capacitance – time related	V _{DS} = 0 to 400 V, V _{GS} = 0 V		20		pF
Q _{OSS}	Output charge	V _{DS} = 400 V, V _{GS} = 0 V		8		nC

E_{OSS}	Output capacitance stored energy	$V_{DS} = 400\text{ V}$, $V_{GS} = 0\text{ V}$, Freq = 100 kHz		1.2		μJ
Gate Characteristics						
Q_G	Gate charge – total	$V_{DS} = 400\text{ V}$ $V_{GS} = 0\text{ to }6\text{ V}$		0.75		nC
Q_{GS}	Gate to source charge			0.13		nC
Q_{GD}	Gate to drain charge			0.4		nC
V_{GPLAT}	Gate plateau voltage	$V_{DS} = 400\text{ V}$ $I_{DS} = 2\text{ A}$		2.5		V
Reverse Conduction Characteristics						
Q_{RR} [4]	Reverse recovery charge			0		nC
t_{RR}	Reverse recovery time			0		ns
V_{SD}	Reverse conduction voltage	$I_{SD} = 1\text{ A}$, $V_{GS} = 0\text{ V}$		2.5		V
		$I_{SD} = 3.5\text{ A}$, $V_{GS} = 0\text{ V}$		4.0		
Switching Time (Refer to Figure 4 and Figure 5)						
t_r	Rise time	$V_{DS} = 400\text{ V}$, $I_{DS} = 2\text{ A}$, $R_U = 20\ \Omega$, $R_D = 5\ \Omega$		14		ns
t_f	Fall time			4		ns
$t_{prop-on}$	Turn-on propagation delay			10		ns
$t_{prop-off}$	Turn-off propagation delay			10		ns

Note:

- [1] V_{GS} refers to the gate-to-source voltage of the power device. Note that the source and the Kelvin-source terminals are internally connected.
- [2] $C_{O(ER)}$ is an equivalent (fixed) capacitance that gives the same energy as C_{OSS} while V_{DS} rises from zero volt to the stated V_{DS} .
- [3] $C_{O(TR)}$ is an equivalent (fixed) capacitance that gives the charging time as C_{OSS} while V_{DS} rises from zero volt to the stated V_{DS} .
- [4] Q_{RR} computation excludes Q_{OSS} .

9.0 About Gate Drive of GaN Power HEMT

9.1 Gate Drive Voltage Level and Slew-rate Control

The GaN HEMT has a recommended gate drive high voltage of +6 V, and hence the gate should operate between 0 to 6 V. A lower than optimum on-state gate drive high voltage, say 5.5 V or 5 V will result into a slightly higher $R_{DS(ON)}$. Before settling to a 6 V on-state voltage, if the gate voltage has some transient ringing (say, with a peak voltage not exceeding 6.5 V), then the device can tolerate this without much adverse effect to the gate reliability. However, excessive ringing, both in magnitude and duration shall be avoided by minimizing the inductance of the gate drive loop. For a high-performance gate drive, the pull-up path and the pull-down path shall be kept separate. Here the pull-up path resistor can be selected for

controlling the turn-on slew-rate. This is similar to what is used for a common silicon power MOSFET. Recommended gate drive interface circuits both with 6 V and 12 V drivers are shown in the section [Application Information](#).

9.2 Immunity Against Parasitic Turn-on, and Use of Negative Gate Drive

Switching produces dv/dt at the switch node, which in the case of GaN can be large. Apart from EMI issues, these large dv/dt may also lead to what is known as parasitic turn-on or Miller turn-on. The way this happens is that when one of the devices in a H-bridge configuration turns-on under hard-switching, the drain-source voltage across the other device undergoes a rapid rise. This positive dv/dt on the drain of the other device (with respect to the gate/source) tries to turn it on through the parasitic gate-to-drain capacitance C_{GD} . This parasitic turn-on is highly undesirable as it can cause catastrophic amount of shoot-through or crowbar current through the H-bridge leg.

One way to avoid parasitic turn-on in GaN HEMT devices is to use a negative-swing gate-drive where under the off condition, the gate drive voltage is a negative voltage in the range of -2 V to -4 V. However, such a drive is more complex to implement and also causes higher losses under reverse conduction. The suggested way to avoid parasitic turn-on for Tagore's TP44400SG devices is to minimize the resistance and the loop inductance of the turn-off path. A good approach to minimize the turn-off resistance is to use a driver with a separate (and strong) turn-off path and use no external resistance in this path.

9.3 Thermal Pad Connection

TP44400SG has a thermal pad which is connected to the die substrate. For a desirable level of thermal performance, the thermal pad needs to be connected to a large PCB area or a suitable heat-sink arrangement. The connection can be either direct or through thermal vias with a pattern as shown in Figure 21. It shall be noted that the thermal pad is electrically LV (low voltage) isolated from the source terminal. The source terminal is brought out separately on Pins 8–10. This allows for an insertion of a current sense resistor at the source without disrupting the main thermal path. However, care shall be exercised that the voltage difference between the TP pad and Pins 8–10 shall not exceed ± 20 V.

9.4 Kelvin Source for Gate Drive Loop

TP44400SG has a separate Kelvin-source pin. This pin should be used for the driver return path for the best de-coupling of the gate-loop from the power-loop.

9.5 Parallel Operation for Higher Current

The TP44400SG device has a maximum current rating as given in Table 3. Higher current operation is possible if two or more TP44400SG devices are connected in parallel. For parallel operation, there are two main challenges: (i) One is the possibility of parasitic divergent oscillations between the parallel devices leading to the permanent failure of the devices. Theoretically, such divergent oscillations can happen in any type of parallel power devices, but due to the extra-high speed of GaN devices more care is needed with them. A major part of fixing such oscillations is to use individual gate resistors for each of

11.0 Typical Characteristics

Conditions: @ $T_J = +25\text{ }^\circ\text{C}$ unless otherwise specified. Plots show behavior of a single device.

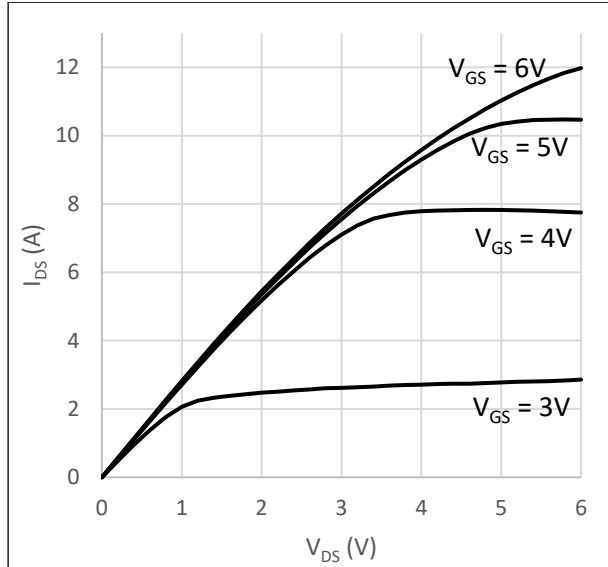


Figure 6 Forward Conduction of GaN HEMT
 $I_{DS} = f(V_{DS}, V_{GS})$

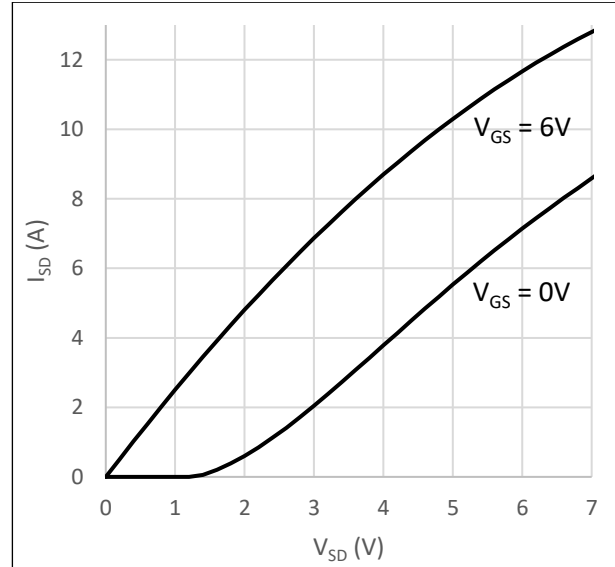


Figure 7 Reverse Conduction of GaN HEMT
 $I_{SD} = f(V_{SD}, V_{GS})$

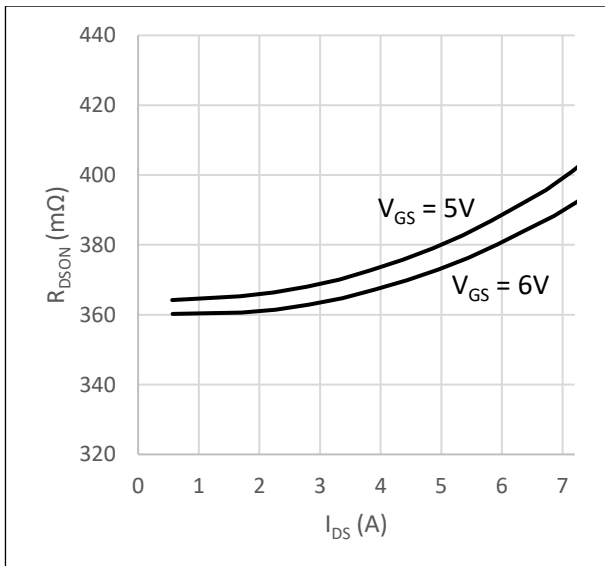


Figure 8 On-state Resistance of GaN HEMT
 $R_{DS(on)} = f(I_{DS}, V_{GS})$

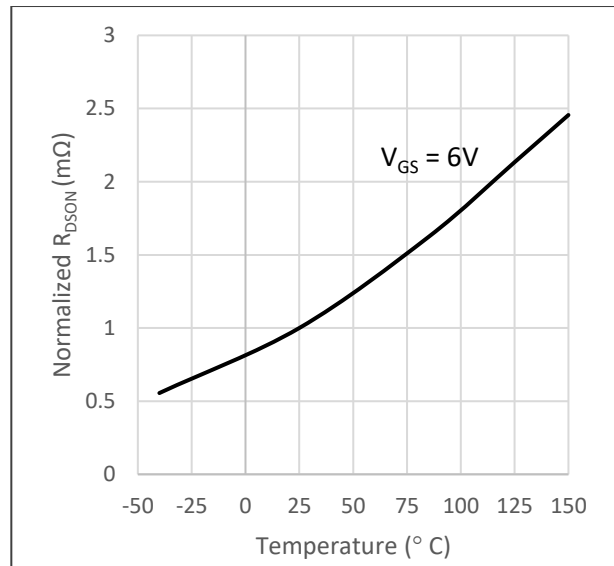


Figure 9 Normalized $R_{DS(on)}$ vs. Junction Temperature at $I_{DS} = 1\text{ A}$

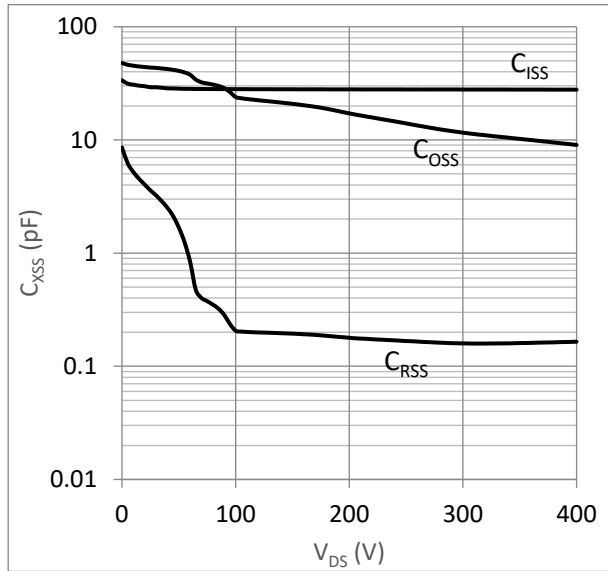


Figure 10 C_{XSS} vs. V_{DS}

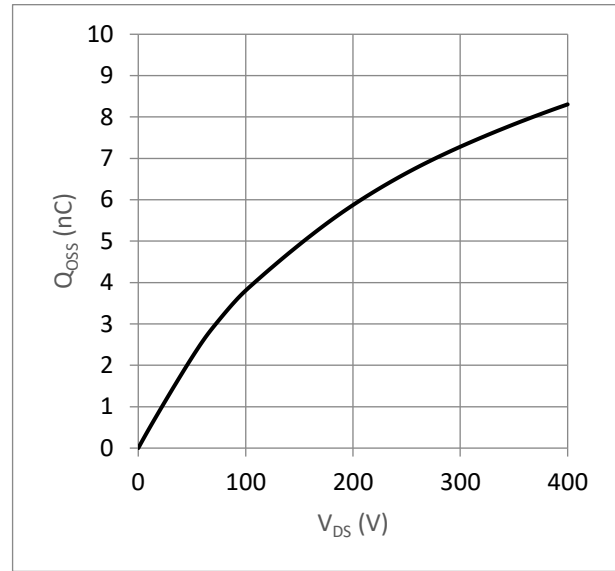


Figure 11 Q_{OSS} vs. V_{DS}

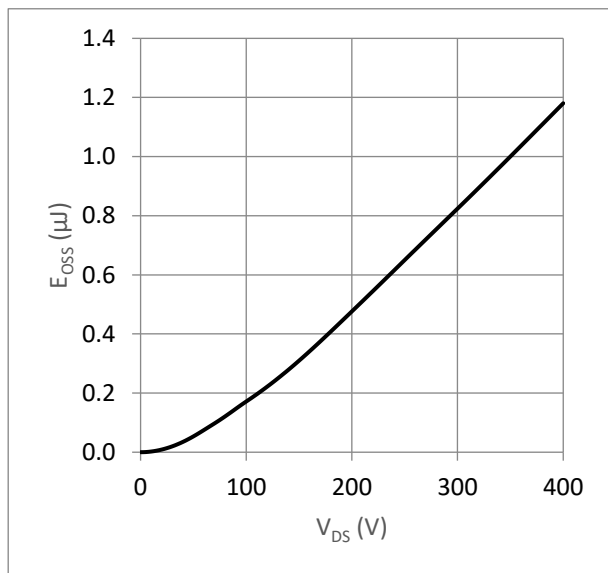


Figure 12 E_{OSS} vs. V_{DS}

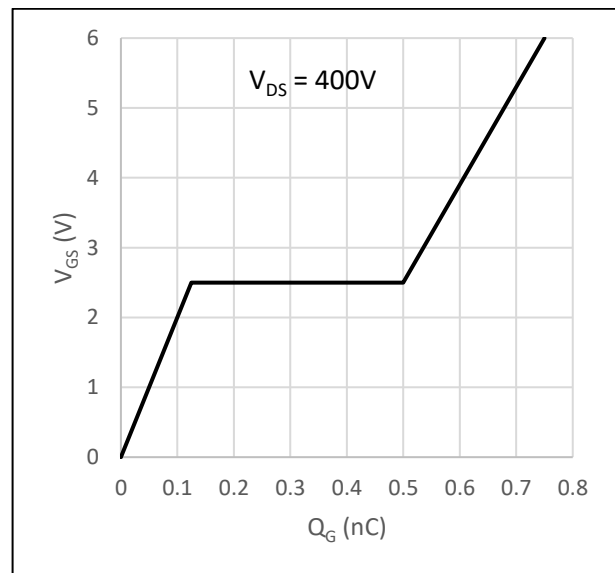


Figure 13 V_{GS} vs. Q_G

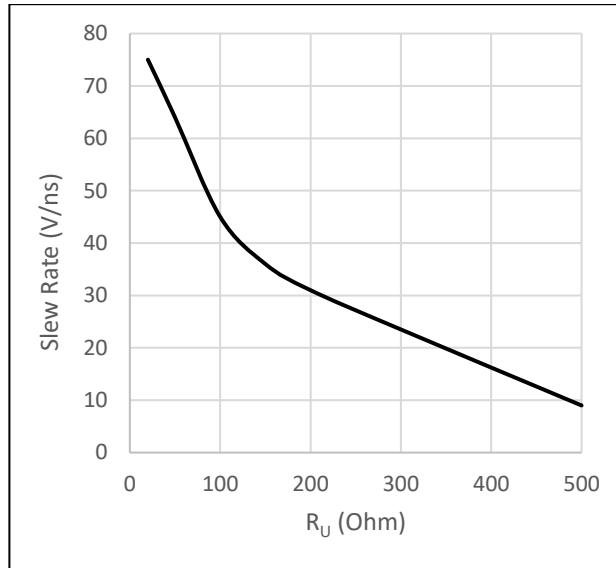


Figure 14 Drain Slew-Rate Variation vs. R_U Resistor at Turn-On Transition ^[1]

Note:

[1] The measurement setup is as per Figure 4 and Figure 5. The slew-rate corresponds to the region where V_{SW} drops from 90% to 10% of the bus voltage during its falling edge transition, and the value of I_{DS} at the transition is 2 A.

12.0 Application Information

12.1 Interface for 6 V Drive

A TP44400SG device can be directly driven with a 6 V driver. However, typically, one needs to control turn-on/off speeds, for which resistors are used. For the common case of a driver with a single output (i.e., no dedicated pull-up and pull-down paths), the interface circuit is shown in the left-side diagram in Figure 15. The resistor R_U provides the path for the turn-on, and its value can be selected for a desirable slew-rate. The turn-off path consists of R_U in parallel with a (Schottky + R_D) combination. The job of the Schottky diode is to ensure that R_D only conducts during the turn-off. Typically, a low value of R_D is preferred in order to avoid Miller turn-on as explained in Section 9.2. For highest turn-off speed, the resistor R_D may be replaced by a short.

Some drivers have separate pull-up and pull-down paths. In such cases, no Schottky diode is needed, and the interface circuit simplifies to what was shown in Figure 4.

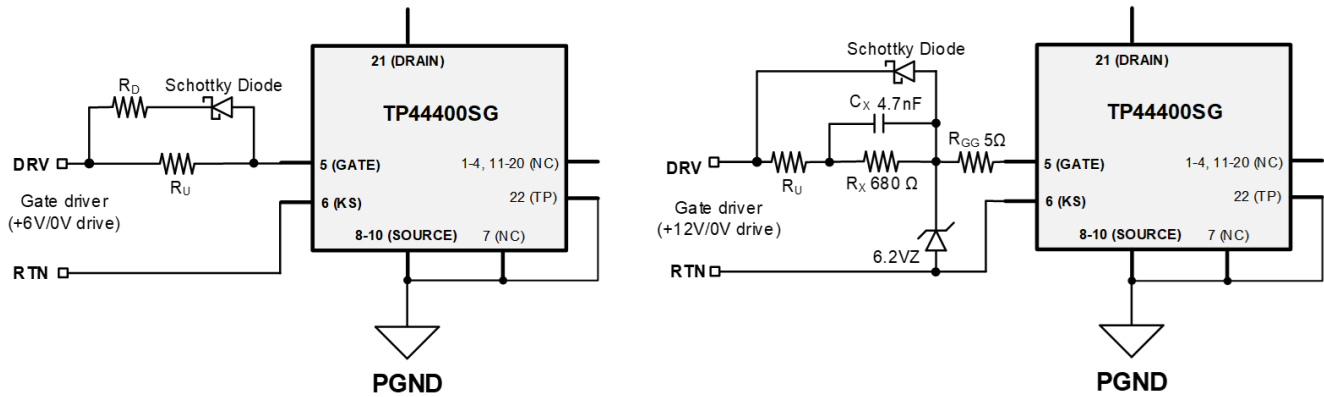


Figure 15 Gate Drive Interface (Left) for 6 V Drive, (Right) for ≥ 12 V Drive

12.2 Interface for ≥ 12 V Drive

When using a higher than 6 V drive (say a standard 12 V or higher), one can use an interface circuit shown in the right-side diagram in Figure 15. The 6.2 V Zener diode serves the purpose of limiting the voltage between the gate and the Kelvin source. The 5 Ω resistor R_{GG} connected to the gate pin is to avoid parasitic oscillation between the GaN device and the Zener diode. For zero volt switching (ZVS) operation, the R_{GG} resistor is optional and may be replaced by a short. The resistor R_U , once again, is for setting the turn-on speed. In this diagram, for the maximum turn-off speed, R_D has been removed by shorting. The Schottky diode remains to provide the fast turn-off path. Finally, within the resistor-capacitor pair R_X - C_X , the resistor limits the Zener current during gate high periods. And the purpose of the capacitor C_X is to bypass R_X during transients so that the turn-on/off speed are not affected by R_X . This interface circuit can be used for drive voltages which are higher than 6 V e.g., 9 V, 12 V, 15 V, etc., and for each of these, R_X may be adjusted as per the desired Zener current.

12.3 Example Application: QRF Charger

Figure 16 shows a typical application diagram of a Quasi Resonant Flyback (QRF) Converter based charger, where TP44400SG GaN is the main switching device. The QRF controller NCP1342 releases +12V/0V PWM at its DRV pin to drive the SUPERIOR GaN. The interface circuit shown in the right-hand portion of Figure 15 is used in this case.

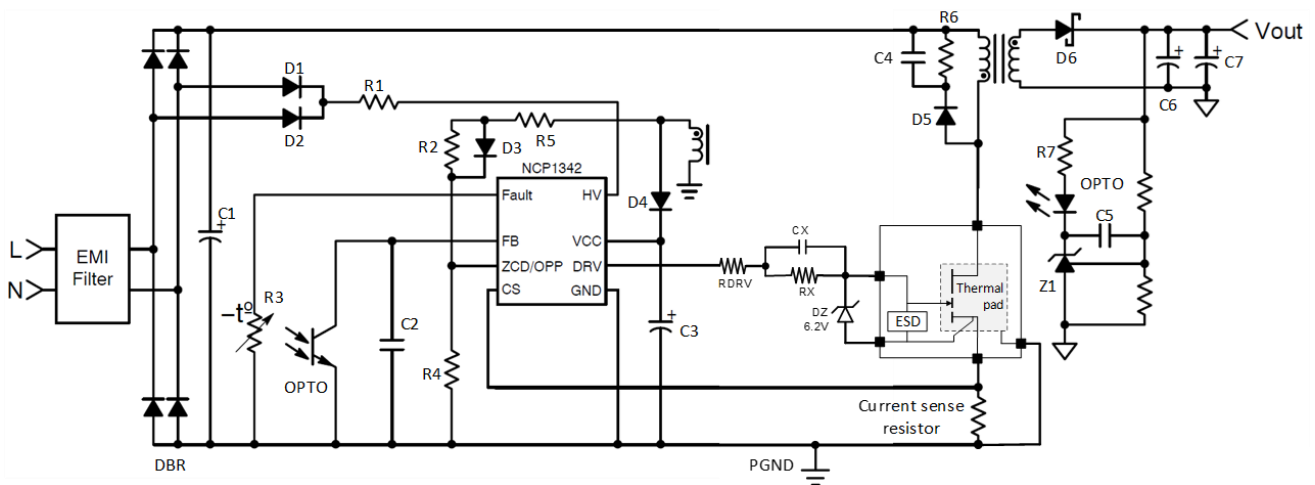
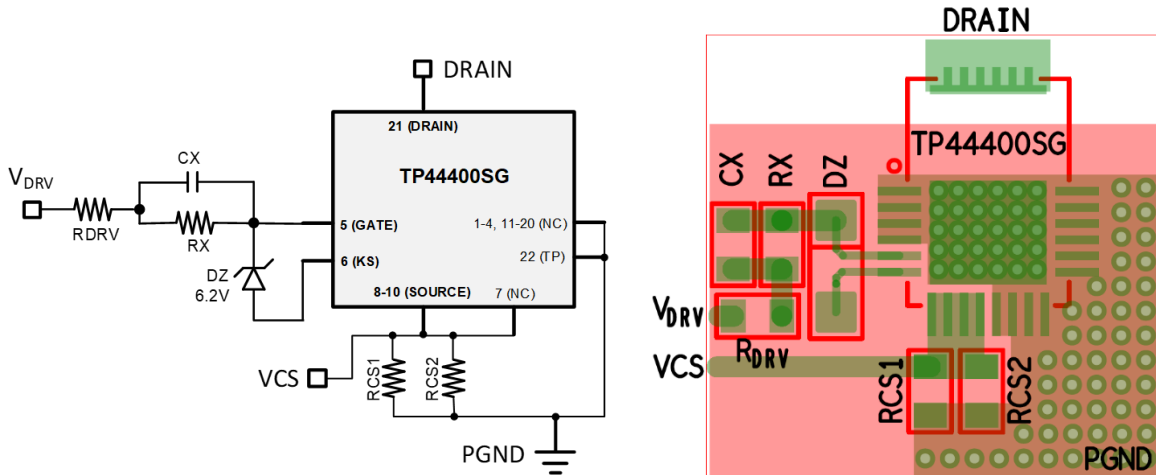


Figure 16 Application Diagram of TP44400SG in a Quasi-Resonant Flyback (QRF) Converter

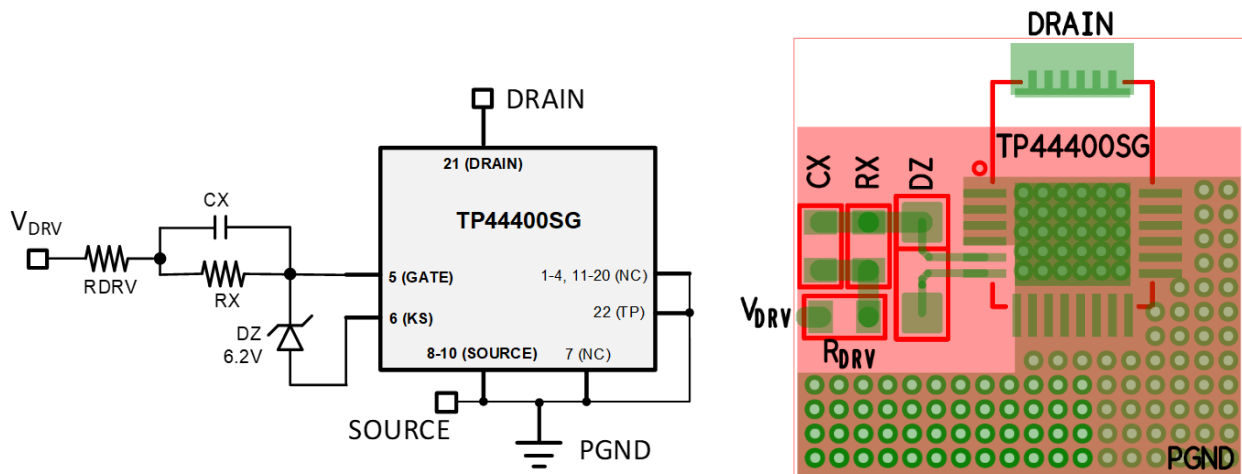
12.4 PCB Layout with and without Current-Sense Resistors

In a converter, it is quite common to use current sense resistors at the source side of the low-side device. Such an arrangement is shown in the top left drawing in Figure 17 with a TP44400SG as the low-side device. The drive interface is for a 12 V driver. While doing the layout for such cases, the thermal pad TP (Pin-22) shall be connected to a large enough area on the PCB (the thermal plane) for heat dissipation. Usually, power-ground (PGND) is the largest copper area available, and the recommended layout is shown in the top right drawing of Figure 17 where PGND acts as the thermal plane. Note that with this arrangement, even with the sense resistor between the source pins and the thermal plane, the thermal performance of the device is minimally affected.

For the case when no sense resistors are used, one could short all the source pins and the NC pins with TP (Pin-22) and use a layout as shown in the bottom right drawing in Figure 17.



(a) With current-sense resistors. IC sits on the green layer of PCB.



(b) Without current-sense resistors. IC sits on the green layer of PCB.

Figure 17 Layout Guidelines for (a) With the Current-Sense Resistors, and (b) Without the Current-Sense Resistors

13.0 Device Package Information

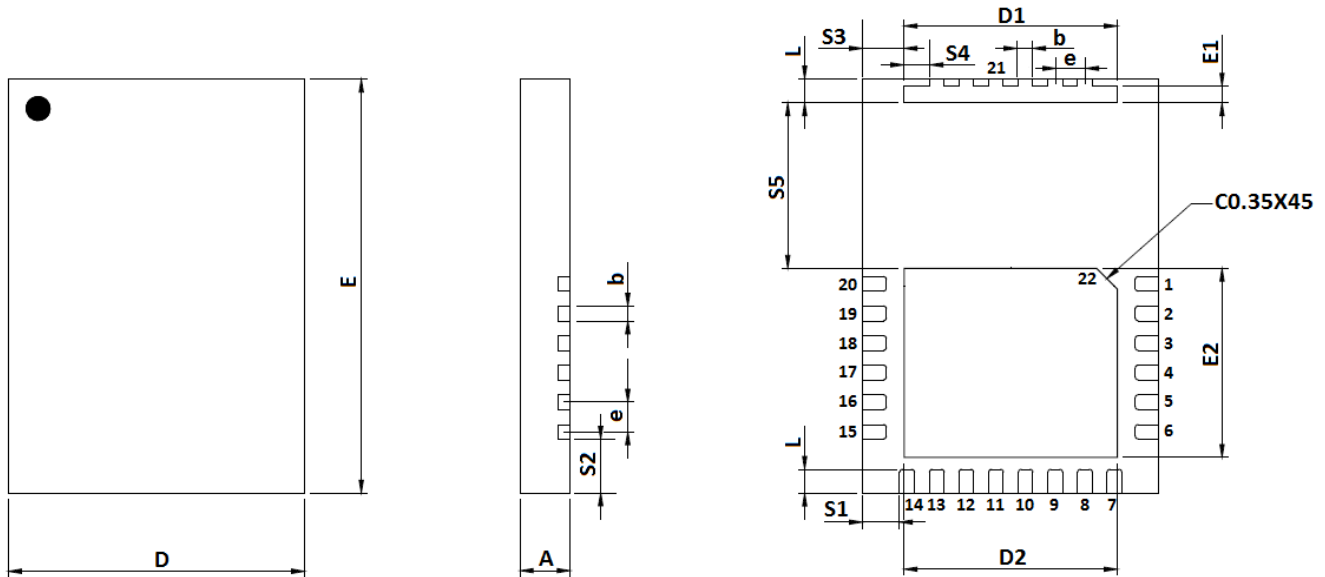


Figure 18 Device Package Drawing
(All dimensions are in mm)

Table 6 Device Package Dimensions

Dimension (mm)	Value (mm)	Tolerance (mm)	Dimension (mm)	Value (mm)	Tolerance (mm)
A	0.80	±0.05	E2	3.20	±0.05
b	0.25	+0.05/-0.07	L	0.40	±0.05
D	5.00 BSC	±0.05	S1	0.625	±0.05
D1	3.60	±0.05	S2	0.91	±0.05
D2	3.60	±0.05	S3	0.70	±0.05
e	0.50 BSC	±0.05	S4	0.425	±0.05
E	7.00 BSC	±0.05	S5	2.80	±0.05
E1	0.28	±0.05	-	-	-

Note: Lead finish: Pure Sn without underlayer; Thickness: 7.5 µm ~ 20 µm (Typical 10 µm ~ 12 µm)

Attention:

Please refer to application notes [TN-001](#) and [TN-002](#) at <http://www.tagoretech.com> for PCB and soldering related guidelines.

15.0 PCB Stencil Design

Guidelines:

- [1] Laser-cut, stainless steel stencil is recommended with electro-polished trapezoidal walls to improve the paste release.
- [2] Stencil thickness is recommended to be 125 μm .

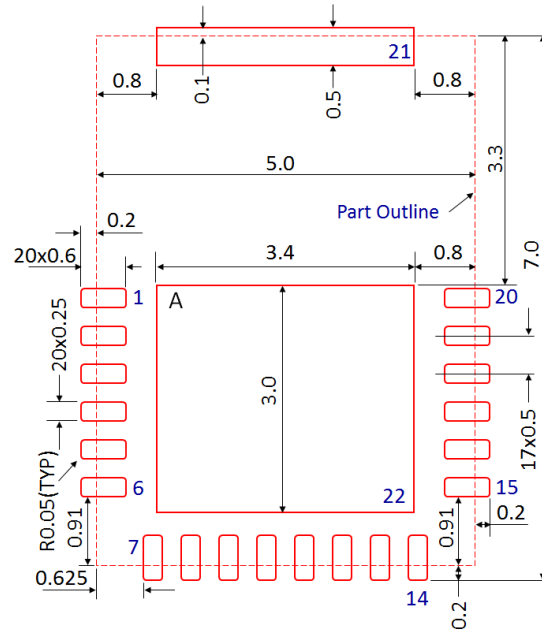


Figure 22 Stencil Openings
(Dimensions are in mm)

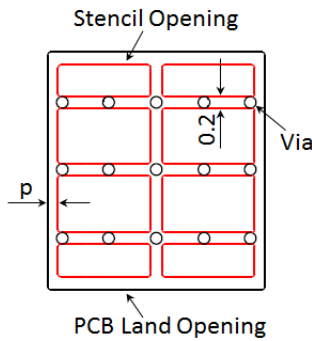


Figure 23 Stencil Openings (Shall Not Cover Via Areas if Possible)
(Dimensions are in mm)

16.0 Tape and Reel Information

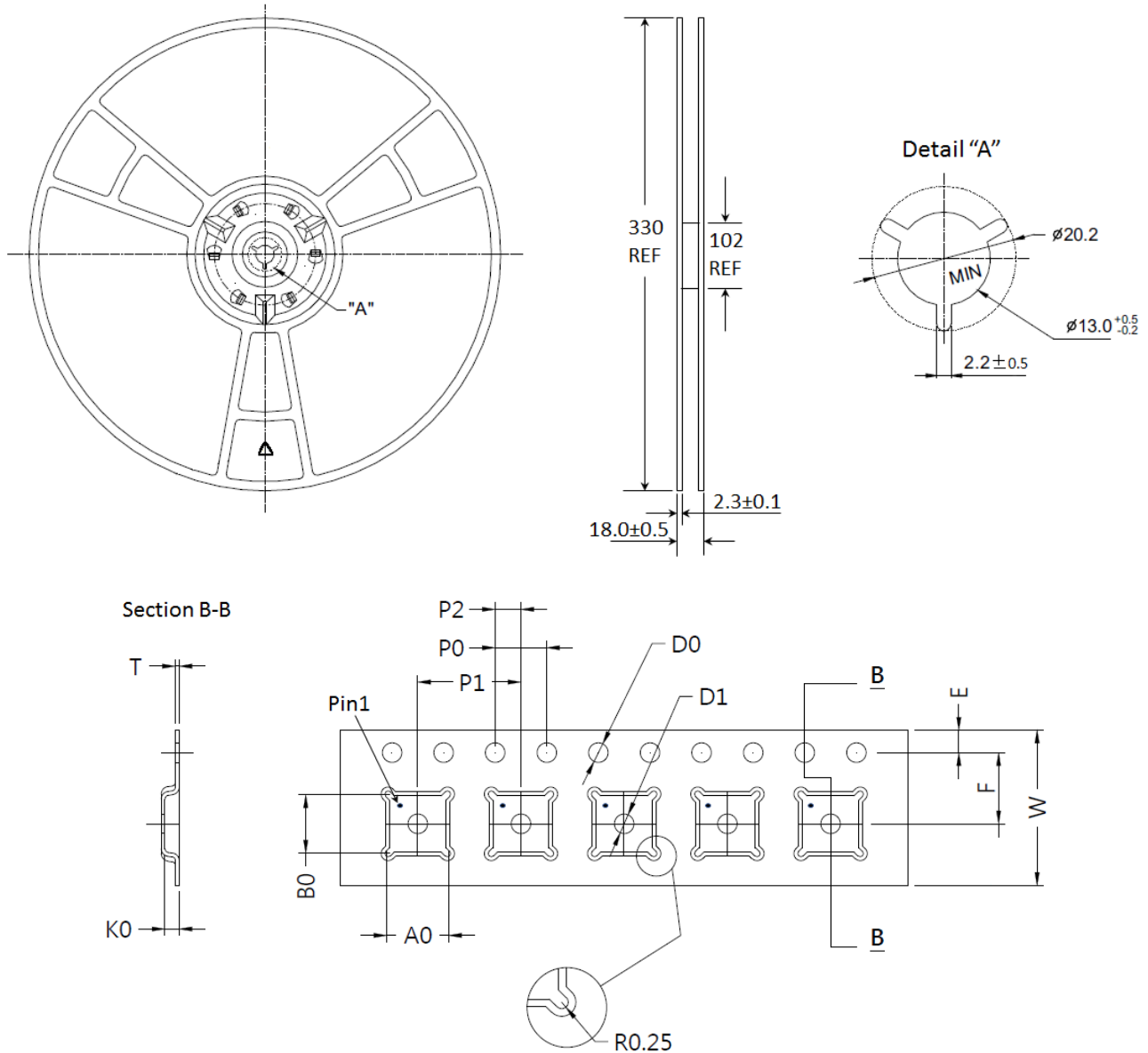


Figure 24 Tape and Reel Drawing

Table 7 Tape and Reel Dimensions

Dimension	Value (mm)	Tolerance (mm)	Dimension	Value (mm)	Tolerance (mm)
A0	10.35	±0.10	K0	1.10	±0.10
B0	8.35	±0.10	P0	4.00	±0.10
D0	1.50	+0.10/-0.00	P1	8.00	±0.10
D1	1.50	+0.10/-0.00	P2	2.00	±0.05
E	1.75	±0.10	T	0.30	±0.05
F	5.50	±0.05	W	12.00	±0.30

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